350 WATT LOW CAPACITANCE TVS ARRAY



DESCRIPTION

The PSLC and PSLCxxC Series of devices are low capacitance TVS arrays available in a SOT-143 package. These devices are designed to protect Ethernet data I/O ports against the damaging effects of ESD and EFT transient threats.

The PSLC series are unidirectional devices used for common mode protection from line to ground. The PSLCxxC series are bidirectional devices typically used for differential mode or common mode protection on balanced lines.

Voltages range from 3.3 to 24 volts for both configurations. Each series provides ESD protection to > 25 kilovolts with a peak pulse power rating of 350 Watts for an 8/20 μ s waveshape. The PSLC and PSLCxxC series are designed to meet and exceed the IEC 61000-4-2 and IEC 61000-4-4 requirements.

FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air 15kV, Contact 8kV
- Compatible with IEC 61000-4-4 (EFT): 40A, 5/50ns
- Compatible with IEC 61000-4-5 (Surge): 12A, 8/20μs Level 1(Line-Gnd) & Level 2(Line-Line)
- 350 Watts Peak Pulse Power per Line (tp = 8/20µs)
- Unidirectional and Bidirectional Configurations
- Protects 1 Line
- · Low Clamping Voltage
- · Low Capacitance: 3pF Typical
- RoHS Compliant
- REACH Compliant

MECHANICAL CHARACTERISTICS

- Molded JEDEC SOT-143 Package
- Approximate Weight: 9 milligrams
- Lead-Free Pure-Tin Plating (Annealed)
- Solder Reflow Temperature:

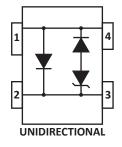
Pure-Tin - Sn, 100: 260-270°C

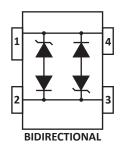
- 8mm Tape and Reel Per EIA Standard 481
- Flammability Rating UL 94V-0

APPLICATIONS

- Ethernet 10/100/1000 Base T
- Cellular Phones
- Audio/Video Inputs
- FireWire, SCSI & USB Interfaces

PIN CONFIGURATIONS





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TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified							
PARAMETER SYMBOL VALUE UNITS							
Operating Temperature	T _L	-55 to 150	°C				
Storage Temperature	T _{stg}	-55 to 150	°C				
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{pp}	350	Watts				

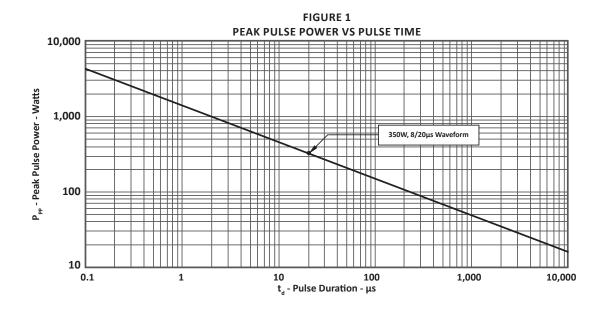
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified								
PART NUMBER (Notes 1 - 2)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V _{WM}	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR)	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ I _p = 5A V _c	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ 8/20μs V _c @ I _{pp}	MAXIMUM LEAKAGE CURRENT @V _{wm} I _D	TYPICAL CAPACITANCE @0V, 1MHz C	
		VOLTS	VOLTS	VOLTS	VOLTS	μΑ	pF	
PSLC03	3U	3.3	4.0	9.0	19.0V @ 20.0A	125	3	
PSLC03C	3B	3.3	4.0	9.0	19.0V @ 20.0A	125	3	
PSLC05	5U	5.0	6.0	11.0	18.3V @ 17.0A	20	3	
PSLC05C	5B	5.0	6.0	11.0	18.3V @ 17.0A	20	3	
PSLC08	8U	8.0	8.5	16.6	18.5V @ 17.0A	10	3	
PSLC08C	8B	8.0	8.5	16.6	18.5V @ 17.0A	10	3	
PSLC12	12U	12.0	13.3	24.0	28.6V @ 11.0A	1	3	
PSLC12C	12B	12.0	13.3	24.0	28.6V @ 11.0A	1	3	
PSLC15	15U	15.0	16.6	30.0	31.8V @ 10.0A	1	3	
PSLC15C	15B	15.0	16.6	30.0	31.8V @ 10.0A	1	3	
PSLC24	24U	24.0	26.7	N/A	56.0V @ 6.0A	1	3	
PSLC24C	24B	24.0	26.7	N/A	56.0V @ 6.0A	1	3	

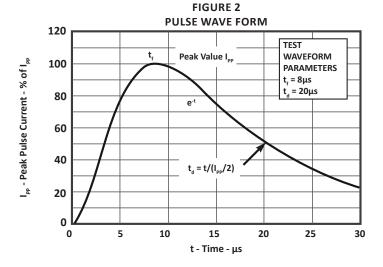
NOTES

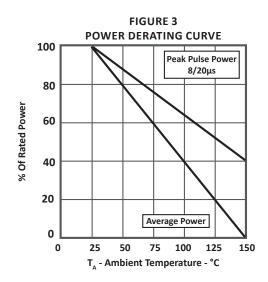
^{1.} Part numbers with an additional "C" suffix are bidirectional devices, i.e., PSLC05 $\underline{\textbf{C}}$.

^{2.} Unidirectional Only: Positive potential is applied from pin 2 to 1 or pin 3 to 4.

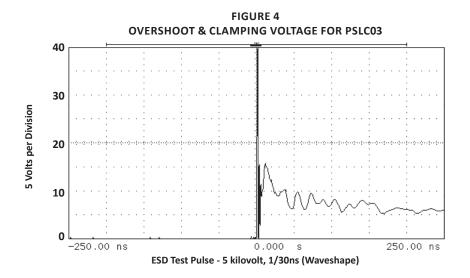
TYPICAL DEVICE CHARACTERISTICS

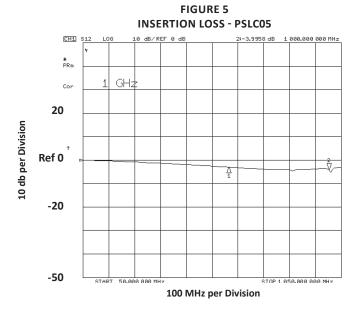


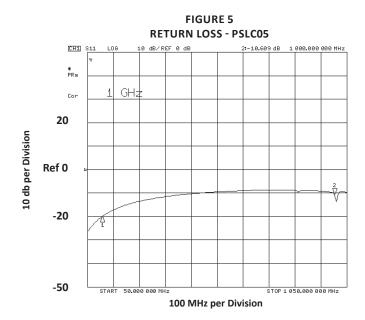




TYPICAL DEVICE CHARACTERISTICS

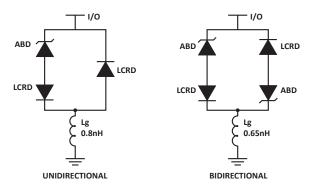






SPICE MODEL

FIGURE 1 SPICE MODEL



ABD - Avalanche Breakdown Diode (TVS) LCRD: Low Capacitance Rectifier Diode Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS							
PARAMETER	UNIT	ABD(TVS)	LCRD				
BV	V	See Table 2	200				
IBV	μΑ	1	0.01				
C _{jo}	pF	See Table 2	5				
I _s	А	See Table 2	1E-13				
Vj	V	0.6	0.6				
М	-	0.33	0.33				
N	-	1	1				
R _s	Ohms	See Table 2	0.31				
TT	S	1E-8	1E-9				
EG	eV	1.11	1.11				

TABLE 2 - ABD SPECIFIC SPICE PARAMETERS								
PART NUMBER	B _v (VOLTS)	C _{io} (pF)	I _s (AMPS)	Rs(OHMS)				
PSLC03	4.5	200	1E-11	0.22				
PSLC05	6.0	140	1E-11	0.18				
PSLC08	8.5	67	1E-11	0.12				
PSLC12	13.3	55	1E-13	1.10				
PSLC15	16.7	47	1E-13	1.43				
PSLC24	26.7	28	1E-13	4.24				
PSLC03C	4.5	200	1E-11	0.22				
PSLC05C	6.0	140	1E-11	0.18				
PSLC08C	8.5	67	1E-11	0.12				
PSLC12C	13.3	55	1E-13	1.10				
PSLC15C	16.7	47	1E-13	1.43				
PSLC24C	26.7	28	1E-13	4.24				

APPLICATION INFORMATION

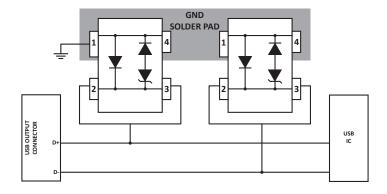


FIGURE 1 - USB PROTECTION

Two PSLCxx (Unidirectional) in a Common-Mode configuration. Circuit connectivity is as follows:

- Device 1: Line 1(D+) is connected to pins 2 and 3.
- Device 2: Line 2(D-) is connected to pins 2 and 3.
- Device 1 and 2: Pins 1 and 4 connected to ground

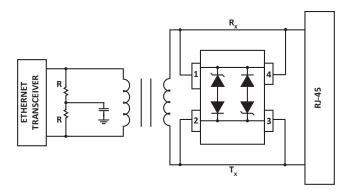


FIGURE 2 - ETHERNET PROTECTION

One PSLCxxC (Bidirectional) in a Differential-Mode configuration. Circuit connectivity is as follow:

- Line 1 (R_x) is connected to pins 1 and 4.
- Line 2 (T_x) is connected to pins 2 and 3.

CIRCUIT BOARD RECOMMENDATIONS

Circuit board layout is critical for electromagnetic compatibility protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.





SOT-143 PACKAGE INFORMATION

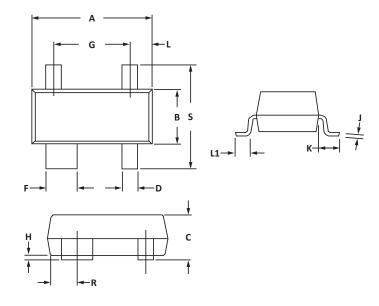
OUTLINE DIMENSIONS							
MILLIN	IETERS	INCHES					
MIN	MAX	MIN	MAX				
2.80	3.04	0.110	0.120				
1.20	1.39	0.047	0.055				
0.84	1.14	0.033	0.045				
0.39	0.50	0.015	0.020				
0.79	0.93	0.031	0.037				
1.78	2.03	0.070	0.080				
0.08	0.15	0.003	0.006				
0.46	0.60	0.018	0.024				
0.445	0.60	0.0175	0.024				
0.40	0.60	0.016	0.024				
0.72	0.83	0.028	0.033				
2.11	2.48	0.083 0.098					
	MILLIN MIN 2.80 1.20 0.84 0.39 0.79 1.78 0.08 0.46 0.445 0.40 0.72	MILLIMETERS MIN MAX 2.80 3.04 1.20 1.39 0.84 1.14 0.39 0.50 0.79 0.93 1.78 2.03 0.08 0.15 0.46 0.60 0.445 0.60 0.40 0.60 0.72 0.83	MILLIMETERS INC MIN MAX MIN 2.80 3.04 0.110 1.20 1.39 0.047 0.84 1.14 0.033 0.39 0.50 0.015 0.79 0.93 0.031 1.78 2.03 0.070 0.08 0.15 0.003 0.46 0.60 0.018 0.445 0.60 0.0175 0.40 0.60 0.016 0.72 0.83 0.028				



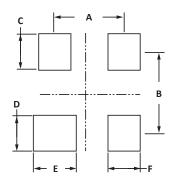
- 1. Dimensioning and tolerances per ANSI Y14.M, 1985.
- 2. Controlling dimension: inches.

1. Controlling dimension: inches.

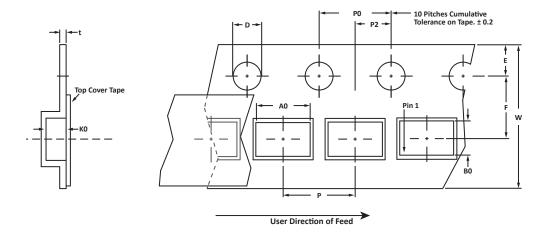
3. Dimensions are exclusive of mold flash and metal burrs.



PAD LAYOUT DIMENSIONS								
DIM	MILLIN	IETERS	INCHES					
	MIN	MAX	MIN	MAX				
А	1.88	2.13	0.074	0.084				
В	1.80	2.06	0.071	0.081				
С	0.71	0.97	0.028	0.038				
D	0.76	1.02	0.030	0.040				
Е	1.07	1.32	0.042	0.052				
F	0.71	0.97	0.028	0.038				
<u> </u>								



TAPE AND REEL



SPECIFICATIONS												
REEL DIA.	TAPE WIDTH	A0	В0	КО	D	E	F	w	P0	P2	Р	tmax
178mm (7")	8mm	3.10 ± 0.10	2.70 ± 0.10	1.35 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25

NOTES

- 1. Dimensions are in millimeters.
- 2. Surface mount product is taped and reeled in accordance with EIA-481.
- 3. Suffix T7 = 7" Reel 3,000 pieces per 8mm tape.
- 4. Suffix T13 = 13" Reel 10,000 pieces per 8mm tape.
- 5. Marking on Part marking code (see page 2) and date code.

Package outline, pad layout and tape specifications per document number 06011.R4 8/10.

ORDERING INFORMATION									
BASE PART NUMBER (xx = Voltage)	I I FADEREF SIIFEIX I TAPE SIIFEIX I OTV/REFI I REFI SI7F I								
PSLCxx/PSLCxxC	-LF	-T7	3,000	7"	n/a				
PSLCxx/PSLCxxC -LF -T13 10,000 13" n/a									
This device is only available in a Lead-Free configuration.									



COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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